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Global Molybdenum Copper Electronic Packaging Material Market Growth 2026-2032

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Abstracts

The global Molybdenum Copper Electronic Packaging Material market size is predicted to grow from US$ 911 million in 2025 to US$ 1349 million in 2032; it is expected to grow at a CAGR of 5.8% from 2026 to 2032.

Molybdenum copper electronic packaging material is a functional composite material based on molybdenum (Mo) and copper (Cu) as basic elements. By adjusting the composition ratio and processing technology, it achieves adjustable coefficient of thermal expansion (CTE), high thermal conductivity, excellent mechanical strength and other characteristics. It is widely used in electronic packaging scenarios such as high-frequency communication and power devices. The core types of molybdenum copper electronic packaging materials are mainly divided into two categories based on structural and functional differences:

Layered composite type: a sandwich structure represented by copper molybdenum copper (Cu/Mo/Cu), with a middle layer of molybdenum or molybdenum copper alloy (thickness accounting for 30% -50%) and an outer layer of high-purity copper. Its thermal conductivity can reach 240-280 W/m ? K, and its CTE can be adjusted to 6.5-8.5 ? 10 ??/K. It has excellent compatibility with silicon chips (4-7 ? 10 ??/K) and can effectively reduce the risk of interface failure caused by thermal stress.

Dispersion composite type: Molybdenum powder and copper powder are mixed and sintered using powder metallurgy technology to form a uniformly distributed biphasic structure. The material has a density of 9.5-10.2 g/cm ? and combines high tensile strength (? 400 MPa) and conductivity (? 45% IACS), making it suitable for packaging substrates in high vibration environments.

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Outstanding thermal management efficiency: The thermal conductivity of molybdenum copper alloy (240-300 W/m ? K) is significantly higher than that of traditional packaging materials (such as 170-200 W/m ? K of aluminum silicon carbide), which can reduce the temperature rise of power devices by 15% -20% and extend their service life. High process adaptability: Foil or sheet materials with a thickness of 0.05-3 mm can be prepared through rolling composite technology, with a surface roughness (Ra) of ? 0.8 ? m. It supports precision processing such as laser cutting and chemical etching, and is suitable for high-density integrated circuit packaging requirements. Strong environmental reliability: Molybdenum has a melting point of 2620 ? C and can withstand working temperatures of 300-500 ? C for a long time in high-temperature packaging scenarios without oxidation or volatilization issues, ensuring the airtightness of the packaging.

The industrial production of molybdenum copper electronic packaging materials mainly relies on two types of technologies:

Rolling composite process: Molybdenum plate and copper foil are metallurgically bonded by hot rolling (temperature 800-950 ? C), with an interface shear strength of ? 80 MPa. The production efficiency is 30% -50% higher than powder metallurgy method, and it is suitable for continuous production of large-sized (? 600 mm wide) plates.

Copper infiltration sintering process: Using molybdenum powder as the matrix (particle size 1-5 ? m), after isostatic pressing, high-temperature copper infiltration (1350-1450 ? C) is carried out. The finished product has a density of ? 98% and a porosity of no more than 1%, which can prepare structural components with complex and irregular shapes.

Molybdenum copper electronic packaging materials have been widely applied in the following fields:

High frequency communication module: In 5G base station RF devices, its low CTE characteristics can reduce signal transmission delay by 10% -15%, and at the same time, through high thermal conductivity design, the junction temperature of the power amplifier chip is controlled within 85 ? C.

Power semiconductor packaging: used as an insulating substrate for IGBT modules, with a thermal resistance of ? 0.15 ? C ? cm ?/W, supporting current density increase to over 200 A/cm ?, meeting the requirements of new energy vehicle electronic control systems.

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Optoelectronic device heat dissipation: In laser diode packaging, the heat dissipation module containing molybdenum copper carrier can improve the stability of optical power output to ? 1.5%, which is suitable for data center optical communication equipment. In 2025, global Molybdenum Copper Electronic Packaging Material production reached approximately 6,800 MT, with an average global market price of around US$ 137 per kg.

The annual production capacity of molybdenum copper electronic packaging materials is 10,000 tons, with a gross profit margin of about 30%.

Upstream: Molybdenum powder; Electrolytic copper or high-purity copper; Powder metallurgy materials; High purity metal materials.

Downstream: high-frequency communication module, power semiconductor packaging, optoelectronic device heat dissipation.

The cost of raw materials is about 55%; The manufacturing and processing cost is about 25%; The cost of equipment and energy consumption is about 10%; The labor and management costs are about 5%; The cost of surface treatment and testing is about 5%.

United States market for Molybdenum Copper Electronic Packaging Material is estimated to increase from US$ million in 2025 to US$ million by 2032, at a CAGR of % from 2026 through 2032.

China market for Molybdenum Copper Electronic Packaging Material is estimated to increase from US$ million in 2025 to US$ million by 2032, at a CAGR of % from 2026 through 2032.

Europe market for Molybdenum Copper Electronic Packaging Material is estimated to increase from US$ million in 2025 to US$ million by 2032, at a CAGR of % from 2026 through 2032.

Global key Molybdenum Copper Electronic Packaging Material players cover ALMT Corp, AMETEK, H.C. Starck Hermsdorf GmbH, Negele Hartmetall-Technik GmbH, Santier, etc. In terms of revenue, the global two largest companies occupied for a share nearly % in 2025.

LP Information, Inc. (LPI) ' newest research report, the ?Molybdenum Copper Electronic

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Packaging Material Industry Forecast? looks at past sales and reviews total world Molybdenum Copper Electronic Packaging Material sales in 2025, providing a comprehensive analysis by region and market sector of projected Molybdenum Copper Electronic Packaging Material sales for 2026 through 2032. With Molybdenum Copper Electronic Packaging Material sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US$ millions of the world Molybdenum Copper Electronic Packaging Material industry.

This Insight Report provides a comprehensive analysis of the global Molybdenum Copper Electronic Packaging Material landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Molybdenum Copper Electronic Packaging Material portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms? unique position in an accelerating global Molybdenum Copper Electronic Packaging Material market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Molybdenum Copper Electronic Packaging Material and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Molybdenum Copper Electronic Packaging Material.

This report presents a comprehensive overview, market shares, and growth opportunities of Molybdenum Copper Electronic Packaging Material market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

Mo60Cu40

Mo75Cu25

Mo80Cu20

Mo85Cu15

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Other

Segmentation by Structure:

Layered Composite Type

Dispersed Composite Type

Segmentation by Preparation Process:

Rolling Composite Process?

Copper Infiltration Sintering Process?

Segmentation by Application:

High Frequency Communication Module

Power Semiconductor Packaging

Heat Dissipation Of Optoelectronic Devices

Other

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

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- APAC
  - China
  - Japan
  - Korea
  - Southeast Asia
  - India
  - Australia
- Europe
  - Germany
  - France
  - UK
  - Italy
  - Russia
- Middle East & Africa
  - Egypt
  - South Africa
  - Israel
  - Turkey
  - GCC Countries

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The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

ALMT Corp

AMETEK

H.C. Starck Hermsdorf GmbH

Negele Hartmetall-Technik GmbH

Santier

ATT Advanced Elemental Materials

Changzhou Fuxi Technology

Changsha Saneway Electronic Materials

Luoyang Combat Tungsten & Molybdenum Materials

Shaanxi Puwei Electronic Technology

ATTL Advanced Materials

Starshining Advanced Materials

Key Questions Addressed in this Report

What is the 10-year outlook for the global Molybdenum Copper Electronic Packaging Material market?

What factors are driving Molybdenum Copper Electronic Packaging Material market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

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How do Molybdenum Copper Electronic Packaging Material market opportunities vary by end market size?

How does Molybdenum Copper Electronic Packaging Material break out by Type, by Application?

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